

TITLE**RESIN IMPREGNATED LAMINATE FOR
WIRING BOARD APPLICATIONS**

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ABSTRACT OF THE INVENTION

Dimensionally stable resin impregnated laminates
for printed wiring board applications are reinforced with
from 43 to 57 weight percent of nonwoven aramid sheet
having a coefficient of thermal expansion of less than 10
10 ppm per °C, a basis weight of from 0.8 to 4.0 oz/yd², a
density of from 0.5 to 1.0 g/cc and a Gurley Hill Porosity
of less than 10 sec.